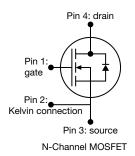


Vishay Siliconix

## **E Series Power MOSFET**





PRODUCT SUMMARY					
V <sub>DS</sub> (V) at T <sub>J</sub> max.	650				
R <sub>DS(on)</sub> typ. (Ω) at 25 °C	V <sub>GS</sub> = 10 V 0.085				
Q <sub>g</sub> max. (nC)	53				
Q <sub>gs</sub> (nC)	11				
Q <sub>gd</sub> (nC)	13				
Configuration	Single				

#### **FEATURES**

- 4<sup>th</sup> generation E series technology
- Low figure-of-merit (FOM) R<sub>on</sub> x Q<sub>g</sub>
- Low effective capacitance (Co(er))
- · Reduced switching and conduction losses
- Avalanche energy rated (UIS)
- · Kelvin connection for reduced gate noise
- Material categorization: for definitions of compliance please see <a href="https://www.vishav.com/doc?99912">www.vishav.com/doc?99912</a>



#### **APPLICATIONS**

- Server and telecom power supplies
- · Switch mode power supplies (SMPS)
- Power factor correction power supplies (PFC)
- Lighting
  - High-intensity discharge (HID)
  - Fluorescent ballast lighting
- Industrial
  - Welding
  - Induction heating
  - Motor drives
  - Battery chargers
  - Solar (PV inverters)

ORDERING INFORMATION	
Package	PowerPAK 8 x 8
Lead (Pb)-free and halogen-free	SiHH100N60E-T1-GE3

ABSOLUTE MAXIMUM RATINGS	(1 <sub>C</sub> = 25 °C, unle	ss otherwis	se noted)		
PARAMETER			SYMBOL	LIMIT	UNIT
Drain-source voltage			$V_{DS}$	600	V
Gate-source voltage			$V_{GS}$	± 30	- V
Continuous drain current (T <sub>J</sub> = 150 °C)	V at 10 V	T <sub>C</sub> = 25 °C T <sub>C</sub> = 100 °C	- I <sub>D</sub>	28	
	V <sub>GS</sub> at 10 V	T <sub>C</sub> = 100 °C		18	А
Pulsed drain current <sup>a</sup>			I <sub>DM</sub>	63	
Linear derating factor				1.38	W/°C
Single pulse avalanche energy b			E <sub>AS</sub>	127	mJ
Maximum power dissipation			$P_{D}$	174	W
Operating junction and storage temperature r	ange		T <sub>J</sub> , T <sub>stg</sub>	-55 to +150	°C
Drain-source voltage slope $T_J = 125 ^{\circ}\text{C}$			dv/dt	100	\//no
Reverse diode dv/dt <sup>c</sup>				50	V/ns

#### Notes

- a. Repetitive rating; pulse width limited by maximum junction temperature
- b.  $V_{DD}$  = 140 V, starting  $T_J$  = 25 °C, L = 28.2 mH,  $R_q$  = 25  $\Omega$ ,  $I_{AS}$  = 3.0 A
- c.  $I_{SD} \le I_D$ , di/dt = 120 A/ $\mu$ s, starting  $T_J$  = 25 °C



# Vishay Siliconix

THERMAL RESISTANCE RATINGS						
PARAMETER SYMBOL TYP. MAX. UNIT						
Maximum junction-to-ambient	R <sub>thJA</sub>	40	42	°C/W		
Maximum junction-to-case (drain)	R <sub>thJC</sub>	0.55	0.72	G/ VV		

PARAMETER	SYMBOL	TEST CONDITIONS		MIN.	TYP.	MAX.	UNIT
Static							
Drain-source breakdown voltage	V <sub>DS</sub>	V <sub>GS</sub> =	= 0 V, I <sub>D</sub> = 250 μA	600	-	-	V
V <sub>DS</sub> temperature coefficient	$\Delta V_{DS}/T_{J}$	Referenc	e to 25 °C, I <sub>D</sub> = 1 mA	-	0.55	-	V/°C
Gate-source threshold voltage (N)	V <sub>GS(th)</sub>	V <sub>DS</sub> =	= V <sub>GS</sub> , I <sub>D</sub> = 250 μA	3.0	-	5.0	V
Onto anima lankana	I <sub>GSS</sub>	$V_{GS} = \pm 20 \text{ V}$		-	-	± 100	nA
Gate-source leakage		,	$V_{GS} = \pm 30 \text{ V}$	-	-	± 1	μΑ
Zana anta nelta sa diseisa anno est		V <sub>DS</sub> =	V <sub>DS</sub> = 600 V, V <sub>GS</sub> = 0 V		-	1	
Zero gate voltage drain current	I <sub>DSS</sub>	V <sub>DS</sub> = 480 V	', V <sub>GS</sub> = 0 V, T <sub>J</sub> = 125 °C	-	-	10	μA
Drain-source on-state resistance	R <sub>DS(on)</sub>	V <sub>GS</sub> = 10 V	I <sub>D</sub> = 13.5 A	-	0.085	0.100	Ω
Forward transconductance <sup>a</sup>	9 <sub>fs</sub>	V <sub>DS</sub> :	= 8 V, I <sub>D</sub> = 13.5 A	-	12	-	S
Dynamic							
Input capacitance	C <sub>iss</sub>		V <sub>GS</sub> = 0 V,	-	1850	-	
Output capacitance	C <sub>oss</sub>	,	$V_{DS} = 100 V$ ,	-	83	-	
Reverse transfer capacitance	C <sub>rss</sub>	f = 1 MHz		-	6	-	pF
Effective output capacitance, energy related <sup>a</sup>	C <sub>o(er)</sub>	V <sub>DS</sub> = 0 V to 480 V, V <sub>GS</sub> = 0 V		-	64	-	
Effective output capacitance, time related <sup>b</sup>	C <sub>o(tr)</sub>			-	410	-	
Total gate charge	Qg				35	53	
Gate-source charge	Q <sub>gs</sub>	$V_{GS} = 10 \text{ V}$ $I_D = 13.5 \text{ A}, V_{DS} = 480 \text{ V}$		-	11	-	nC
Gate-drain charge	$Q_{gd}$				13	-	
Turn-on delay time	t <sub>d(on)</sub>			-	26	52	
Rise time	t <sub>r</sub>	$V_{DD} =$	V <sub>DD</sub> = 480 V, I <sub>D</sub> = 13.5 A,		54	81	no
Turn-off delay time	t <sub>d(off)</sub>	V <sub>GS</sub> =	= 10 V, $R_g = 9.1 \Omega$	-	41	82	ns
Fall time	t <sub>f</sub>			-	41	82	
Gate input resistance	$R_g$	f = 1	MHz, open drain	0.3	0.6	1.2	Ω
<b>Drain-Source Body Diode Characteristic</b>	s						
Continuous source-drain diode current	I <sub>S</sub>	MOSFET symbol showing the integral reverse p - n junction diode		-	-	28	
Pulsed diode forward current	I <sub>SM</sub>			-	-	63	A
Diode forward voltage	V <sub>SD</sub>	T <sub>J</sub> = 25 °C, I <sub>S</sub> = 13.5 A, V <sub>GS</sub> = 0 V		-	-	1.2	V
Reverse recovery time	t <sub>rr</sub>			-	345	690	ns
Reverse recovery charge	Q <sub>rr</sub>	T <sub>J</sub> = 25 °C, $I_F = I_S = 13.5 \text{ A}$ , di/dt = 100 A/ $\mu$ s, $V_R = 25 \text{ V}$		-	5.0	10	μC
Reverse recovery current	I <sub>RRM</sub>			_	24	-	Α

#### Notes

- a.  $C_{oss(er)}$  is a fixed capacitance that gives the same energy as  $C_{oss}$  while  $V_{DS}$  is rising from 0 % to 80 %  $V_{DSS}$
- b.  $C_{oss(tr)}$  is a fixed capacitance that gives the same charging time as  $C_{oss}$  while  $V_{DS}$  is rising from 0 % to 80 %  $V_{DSS}$



### TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

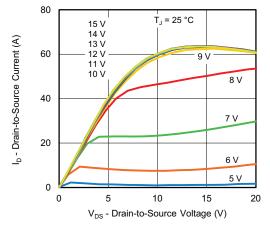


Fig. 1 - Typical Output Characteristics

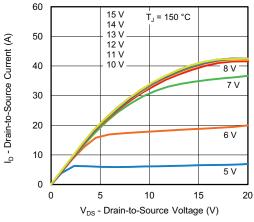


Fig. 2 - Typical Output Characteristics

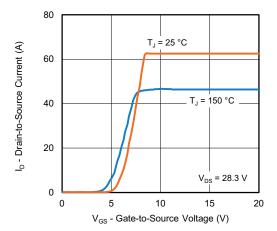


Fig. 3 - Typical Transfer Characteristics

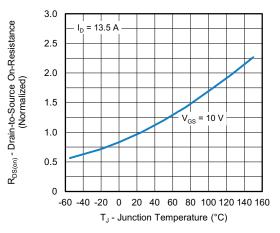


Fig. 4 - Normalized On-Resistance vs. Temperature

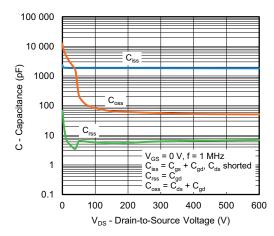


Fig. 5 - Typical Capacitance vs. Drain-to-Source Voltage

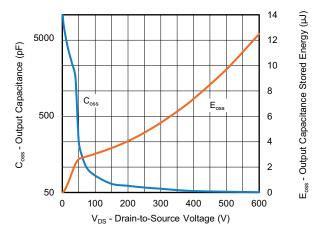


Fig. 6 - Coss and Eoss vs. VDS



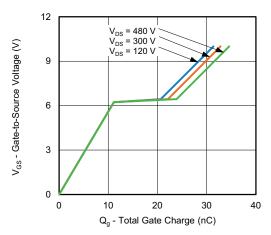


Fig. 7 - Typical Gate Charge vs. Gate-to-Source Voltage

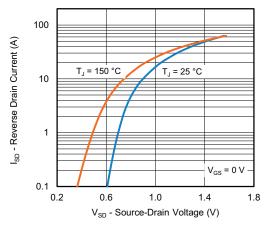


Fig. 8 - Typical Source-Drain Diode Forward Voltage

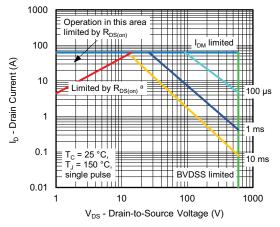


Fig. 9 - Maximum Safe Operating Area



a. V<sub>GS</sub> > minimum V<sub>GS</sub> at which R<sub>DS(on)</sub> is specified

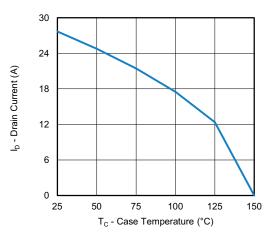


Fig. 10 - Maximum Drain Current vs. Case Temperature

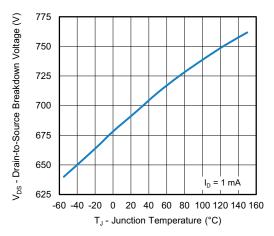


Fig. 11 - Temperature vs. Drain-to-Source Voltage



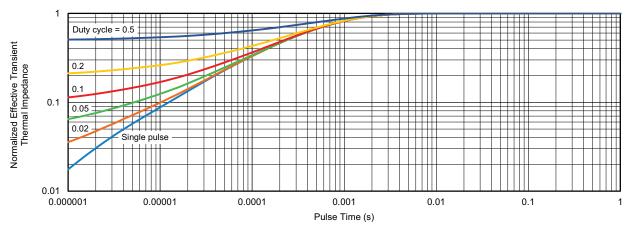


Fig. 12 - Normalized Transient Thermal Impedance, Junction-to-Case

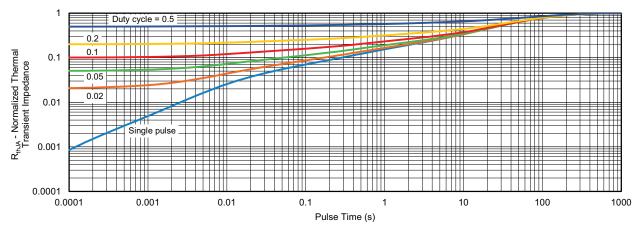


Fig. 13 - Normalized Thermal Transient Impedance, Junction-to-Ambient

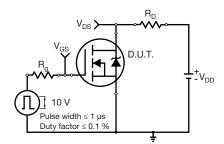


Fig. 14 - Switching Time Test Circuit

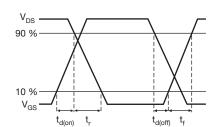


Fig. 15 - Switching Time Waveforms



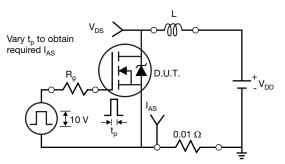


Fig. 16 - Unclamped Inductive Test Circuit

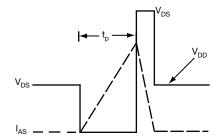


Fig. 17 - Unclamped Inductive Waveforms

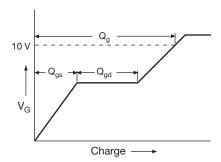


Fig. 18 - Basic Gate Charge Waveform

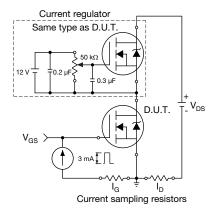
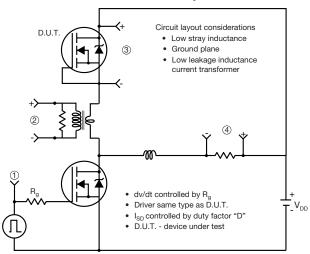


Fig. 19 - Gate Charge Test Circuit



#### Peak Diode Recovery dv/dt Test Circuit



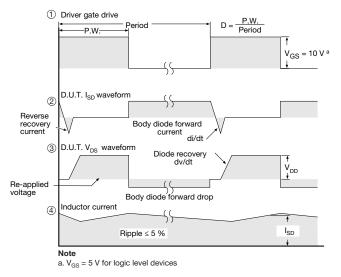


Fig. 20 - For N-Channel

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# PowerPAK® 8 x 8 Case Outline







DIM	MILLIMETERS			INCHES			
DIM.	MIN.	NOM.	MAX.	MIN.	NOM.	MAX.	
А	0.95	1.00	1.05	0.037	0.039	0.041	
A1	0.00	-	0.05	0.000	-	0.002	
A2	020 ref.		0.008 ref.				
b	0.95	1.00	1.05	0.037	0.039	0.041	
D	7.90	8.00	8.10	0.311	0.315	0.319	
D2	7.10	7.20	7.30	0.280	0.283	0.287	
D3	0.40 BSC		0.016 BSC				
е		2.00 BSC		0.079 BSC			
Е	7.90	8.00	8.10	0.311	0.315	0.319	
E2	4.30	4.35	4.40	0.169	0.171	0.173	
E3		0.40 BSC		0.016 BSC			
K	2.75 BSC		0.108 BSC				
L	0.45	0.50	0.55	0.018	0.020	0.022	
N <sup>(3)</sup>	8				8		

#### Notes

- (1) Use millimeters as the primary measurement
- (2) Dimensioning and tolerances conform to ASME Y14.5 M 1994
- (3) N is the number of terminals
- (4) The pin 1 identifier must be existed on the top surface of the package by using indentation mark or other feature of package body
- (5) Exact shape and size of this feature is optional

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DWG: 6041

Revision: 28-Sep-2020 1 Document Number: 67859



# Recommended Minimum PADs for PowerPAK® 8 mm x 8 mm



Dimensions in millimeters



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